



Process Change Notification

PCN Number: PCN-2021-150

PCN Notification Date: 06/19/2023

Final PCN

Lead Frame Supplier Source change to support the 28L SSOP component material

Dear Customer,

This is the Final Product Change Notification (PCN) for the Lead Frame supplier source of 28L SSOP component material from ASM (ASM Materials China LTD - CHINA) to PoongSan (PoongSan SanJia Microtec CO., LTD – CHINA).

Note: This is the subsequent notification to the Initial PCN distributed November 2021

The described change(s) within this PCN will take immediate effect as the Cirrus Logic qualification has been successfully completed. The describe change is a running change.

Cirrus Logic would like to take this opportunity to thank our customers for their cooperation and assistance in this respective matter. Any specific or immediate inquiries should be directed to your local Field Sales Representative.

Sincerely,

Quality Systems Administrator
Cirrus Logic Corporate Quality
Phone: +1(512) 851-4000



Process Change Notification

PCN Number: PCN-2021-150

PCN Notification Date: 06/19/2023

Products Affected:

The devices listed on this page are the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

Technical details of this Process / Product Change follow on the next page(s).

Title:		Lead Frame Supplier Source change to support the 28L SSOP component material			
Customer Contact:		Local Field Sales Representative	Phone:	(512) 851-4000	Dept: Corporate Quality
Proposed 1st Ship Date:		Running Change	Estimated Sample Availability Date:		Not Applicable
	Assembly Site		Assembly Process		Assembly Materials
	Wafer Fab Site		Wafer Fab Process		Wafer Fab Materials
	Wafer Bump Site		Wafer Bump Process		Wafer Bump Material
	Test Site		Test Process		Design
	Electrical Specification		Mechanical Specification		Part Number
	Packing/Shipping/Labeling	X	Other		Data Sheet
Comments:		Lead Frame Material Supplier Change			

PCN Details

Description of Change:

Lead Frame Material Supplier Change:

- **From:** ASM (ASM Materials China LTD - CHINA)
- **To:** PoongSan (PoongSan SanJia Microtec CO., LTD – CHINA)
 - **Note:** PoongSan (PoongSan SanJia Microtec CO., LTD – CHINA) is already a qualified lead frame supplier for Cirrus Logic

Special Note: Items Remaining the Same

- **POD (Package Outline Drawing) Dimensions**
Remain the same: **All dimensions are within JEDEC MO-150b requirements.**
Reference Appendix A
- **Lead Frame Material:**
Remains the same: C194
- **Mold Compound Material:**
Remains the same: Sumitomo EME-G700
- **DIE Attach Material:**
Remains the same: Ablebond 8290
- **Moisture Sensitivity Level (MSL):**
Remains the same: MSL 3



Process Change Notification

PCN Number: PCN-2021-150

PCN Notification Date: 06/19/2023

Reason for Change:

Maintain continuity of material supply.

Anticipated Impact on Form, Fit, Function, Quality or Reliability:

No anticipated adverse impact to the quality and/or reliability of said product.

Anticipated Impact on Material Declaration:

- ☒ No Impact to the Material Declaration ☐ Material Declarations or Product Content reports are driven from production data and will be available following the production release.

Product Affected:

Device	Cirrus Logic Orderable Part Number
1	CS5464K-ISZ
2	CS5464K-ISZR
3	CS5467K-ISZ
4	CS5467K-ISZR
5	CS5451A-ISZ
6	CS5451A-ISZR

Changes To Product Identification Resulting From This PCN:

There are no changes to the production identification

PCN Number: PCN-2021-150

PCN Notification Date: 06/19/2023

The Qualification Plans are designed using JEDEC and other applicable industry standards. An overall summary of the Qualification results will be submitted upon completion.

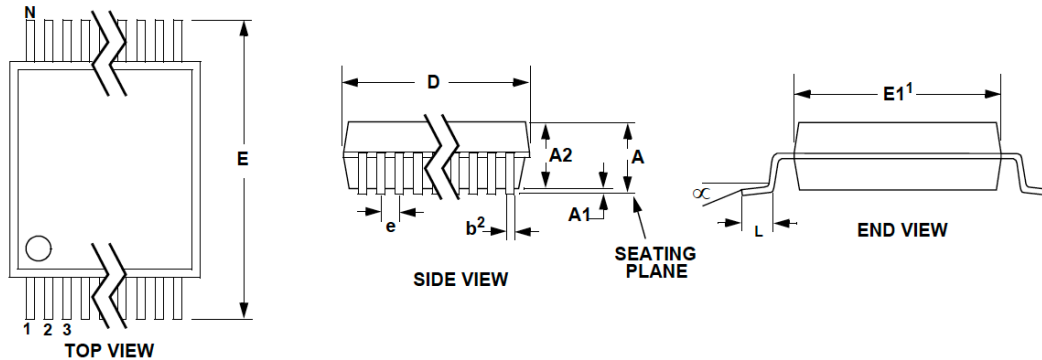
Qualification Plan

CS5451A-ISZ Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results			
Reliability Test	Standard	Conditions	Sample Size (PASS/FAIL)
WBP (Wire Bond Pull)	MIL-STD-883 Method 2011	Paragraph 3 (Procedure) (3 Lots – 5 units / Lot)	15 (Zero Fails)
WBS (Wire Bond Shear)	JESD22 B116	Paragraph 4 (Procedure) (3 Lots – 5 units / Lot)	15 (Zero Fails)
SD (Solderability)	JESD22 B102	245°C / 8 hr steam age before SD (3 Lots – 5 units / Lot)	15 (Zero Fails)
PD (Physical Dimensions)	JESD22 B100 + B108	Package outline per JESD95 Cpk > 1.50 per JESD95 (1 Lot – 30 units)	30 (Zero Fails)
PC + TC (MSL3 + Temperature Cycle)	JEDEC J-STD-020A + JESD22 A104	Condition C (-65°C / +150°C) Air to Air (3 Lots – 77 units / Lot) Read Point – 500 Cycles Post Pre-Condition	231 (Zero Fails)
Notes: <ul style="list-style-type: none"> Qualification tests “pass” on zero fails for each test. CS5451A-ISZR serves as the Qualification Vehicle for the 28L SSOP Lead Frame Material. Reliability Qualification Results: <ul style="list-style-type: none"> Successful Qualification Completion - Zero Fails 			

APPENDIX A – POD (PACKAGE OUTLINE DRAWING) DIMENSIONS

*All dimensions are within JEDEC MO-150b requirements

28L SSOP PACKAGE DRAWING



DIM	INCHES			MILLIMETERS			NOTE
	MIN	NOM	MAX	MIN	NOM	MAX	
A	--	--	0.084	--	--	2.13	
A1	0.002	0.006	0.010	0.05	0.15	0.25	
A2	0.064	0.069	0.074	1.62	1.75	1.88	
b	0.009	--	0.015	0.22	--	0.38	2,3
D	0.390	0.4015	0.413	9.90	10.20	10.50	1
E	0.291	0.307	0.323	7.40	7.80	8.20	
E1	0.197	0.209	0.220	5.00	5.30	5.60	1
e	0.022	0.026	0.030	0.55	0.65	0.75	
L	0.025	0.0354	0.041	0.63	0.90	1.03	
∞	0°	4°	8°	0°	4°	8°	

JEDEC #: MO-150

Controlling Dimension is Millimeters

- Notes:
1. "D" and "E1" are reference datums and do not include mold flash or protrusions, but do include mold mismatch and are measured at the parting line, mold flash or protrusions shall not exceed 0.20 mm per side.
 2. Dimension "b" does not include dambar protrusion/intrusion. Allowable dambar protrusion shall be 0.13 mm total in excess of "b" dimension at maximum material condition. Dambar intrusion shall not reduce dimension "b" by more than 0.07 mm at least material condition.
 3. These dimensions apply to the flat section of the lead between 0.10 and 0.25 mm from lead tips.